GigaDevice Semiconductor Inc.

Device Limitations of GDSCN832xx

Errata Sheet

Revision 1.0

(Aug. 2025)



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1. Introduction

This document applies to GDSCN832xx product series, as shown in <u>Table 1-1. Applicable</u> <u>products</u>. It offers technical guidance for using GDSCN832xx and provides workaround to current device limitations.

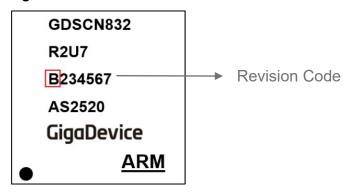
Table 1-1. Applicable products

Туре	Part Numbers
ASIC	GDSCN832xx series

1.1. Revision identification

The device revision can be identified according to the mark on the top of the package. The 1st code on Line 3 of the mark is the product revision code, as shown in <u>Figure 1-1. Device</u> <u>revision code of GDSCN832xx</u>.

Figure 1-1. Device revision code of GDSCN832xx



1.2. Summary of device limitations

The device limitations of GDSCN832XX are shown in <u>Table 1-2. Device limitations</u>, please refer to Section 2 for more details.

Table 1-2. Device limitations

Module	Limitations	Workaround
Wodule		Rev. Code B
	Under the default configuration, the external MCU (I2C master)	
GPIO	cannot access the EEPROM via the EESDA / EESCL pins of the	Υ
	ESC chip	

Note:

Y = Limitation present, workaround available

N = Limitation present, no workaround available

'--' = Limitation fixed



2. Descriptions of device limitations

2.1. **GPIO**

2.1.1. Under the default configuration, the external MCU (I2C master) cannot access the EEPROM via the EESDA / EESCL pins of the ESC chip

Description & impact

When using an external MCU to access the EEPROM, the EESDA / EESCL pins of the ESC chip are set to push-pull mode by default, which prevents the external MCU from reading EEPROM data. In this case, the ESC chip can still access the EEPROM normally, and its functionality remains unaffected.

Workarounds

The external MCU can access the EEPROM only after configuring the EESDA / EESCL pins of the ESC chip to open-drain output mode through the PDI interface.



3. Revision history

Table 3-1. Revision history

Revision No.	Description	Date
1.0	Initial Release	Aug.8 2025



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